



SOT1144-1

plastic thermal enhanced very thin quad flat package; no leads; 42 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN42
Package type industry code	HVQFN42
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	28-8-2009

Table 1. Package summary

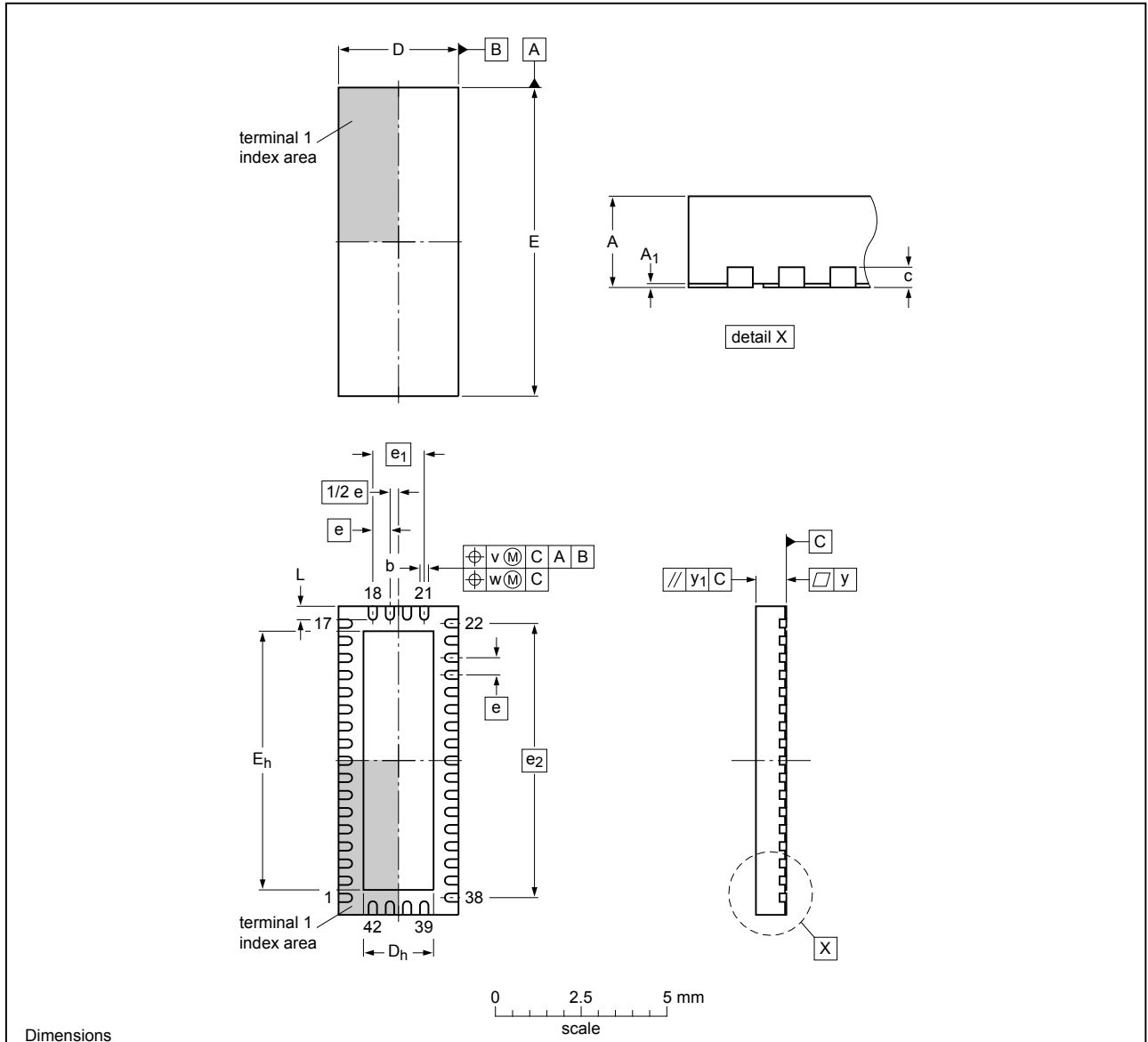
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.5	3.6	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	0.85	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	42	-	



2. Package outline

HVQFN42: plastic thermal enhanced very thin quad flat package; no leads; 42 terminals; body 3.5 x 9 x 0.85 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	b	c	D	D _h	E	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	1.00	0.05	0.30		3.6	2.15	9.1	7.70				0.5				
mm nom	0.85	0.02	0.25	0.2	3.5	2.05	9.0	7.55	0.5	1.5	8.0	0.4	0.1	0.05	0.05	0.1
min	0.80	0.00	0.20		3.4	1.95	8.9	7.40				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1144-1	---	---	---		-09-08-28- 11-08-23

Fig. 1. Package outline HVQFN42 (SOT1144-1)

3. Legal information

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